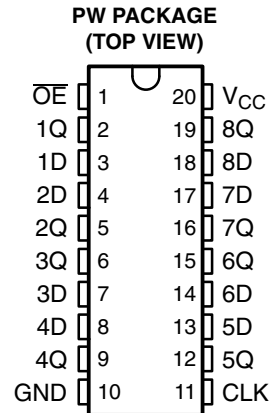


# SN74LV374A-Q1 OCTAL EDGE-TRIGGERED D-TYPE FLIP-FLOP WITH 3-STATE OUTPUTS

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- **Qualified for Automotive Applications**
- **Typical  $V_{OLP}$  (Output Ground Bounce)**  
<0.8 V at  $V_{CC} = 3.3$  V,  $T_A = 25^\circ\text{C}$
- **Typical  $V_{OHV}$  (Output  $V_{OH}$  Undershoot)**  
>2.3 V at  $V_{CC} = 3.3$  V,  $T_A = 25^\circ\text{C}$
- **Supports Mixed-Mode Voltage Operation on All Ports**
- **$I_{off}$  Supports Partial-Power-Down Mode Operation**
- **ESD Protection Exceeds JESD 22**
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)
  - 1000-V Charged-Device Model (C101)



## description/ordering information

The SN74LV374A is an octal edge-triggered D-type flip-flop designed for 2-V to 5.5-V  $V_{CC}$  operation.

This device features 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. It is particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

On the positive transition of the clock (CLK) input, the Q outputs are set to the logic levels set up at the data (D) inputs.

A buffered output-enable ( $\overline{OE}$ ) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and the increased drive provide the capability to drive bus lines without need for interface or pullup components.

$\overline{OE}$  does not affect internal operations of the latch. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

This device is fully specified for partial-power-down applications using  $I_{off}$ . The  $I_{off}$  circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

## ORDERING INFORMATION†

$T_A$	PACKAGE‡		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 105°C	TSSOP – PW	Tape and reel	SN74LV374ATPWQR1	LV374ATQ

† For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at <http://www.ti.com>.

‡ Package drawings, thermal data, and symbolization are available at <http://www.ti.com/packaging>.



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

**TEXAS  
INSTRUMENTS**

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# SN74LV374A-Q1

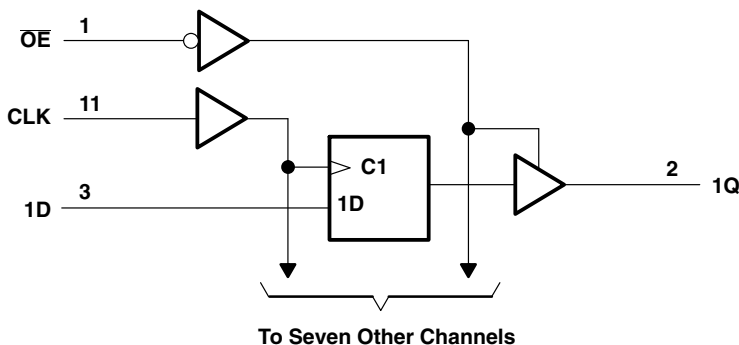
## OCTAL EDGE-TRIGGERED D-TYPE FLIP-FLOP WITH 3-STATE OUTPUTS

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FUNCTION TABLE  
(each flip-flop)

INPUTS			OUTPUT
OE	CLK	D	Q
L	↑	H	H
L	↑	L	L
L	L	X	Q <sub>0</sub>
H	X	X	Z

### logic diagram (positive logic)



### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Supply voltage range, $V_{CC}$	-0.5 V to 7 V
Input voltage range, $V_I$ (see Note 1)	-0.5 V to 7 V
Voltage range applied to any output in the high-impedance or power-off state, $V_O$ (see Note 1)	-0.5 V to 7 V
Output voltage range, $V_O$ (see Notes 1 and 2)	-0.5 V to $V_{CC} + 0.5$ V
Input clamp current, $I_{IK}$ ( $V_I < 0$ )	-20 mA
Output clamp current, $I_{OK}$ ( $V_O < 0$ )	-50 mA
Continuous output current, $I_O$ ( $V_O = 0$ to $V_{CC}$ )	±35 mA
Continuous current through $V_{CC}$ or GND	±70 mA
Package thermal impedance, $\theta_{JA}$ (see Note 3)	83°C/W
Storage temperature range, $T_{stg}$	-65°C to 150°C

<sup>†</sup> Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES:
1. The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
  2. This value is limited to 5.5 V maximum.
  3. The package thermal impedance is calculated in accordance with JESD 51-7.

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## OCTAL EDGE-TRIGGERED D-TYPE FLIP-FLOP WITH 3-STATE OUTPUTS

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### recommended operating conditions (see Note 4)

		MIN	MAX	UNIT	
$V_{CC}$	Supply voltage	2	5.5	V	
$V_{IH}$	High-level input voltage	$V_{CC} = 2\text{ V}$	1.5	V	
		$V_{CC} = 2.3\text{ V to }2.7\text{ V}$	$V_{CC} \times 0.7$		
		$V_{CC} = 3\text{ V to }3.6\text{ V}$	$V_{CC} \times 0.7$		
		$V_{CC} = 4.5\text{ V to }5.5\text{ V}$	$V_{CC} \times 0.7$		
$V_{IL}$	Low-level input voltage	$V_{CC} = 2\text{ V}$	0.5	V	
		$V_{CC} = 2.3\text{ V to }2.7\text{ V}$	$V_{CC} \times 0.3$		
		$V_{CC} = 3\text{ V to }3.6\text{ V}$	$V_{CC} \times 0.3$		
		$V_{CC} = 4.5\text{ V to }5.5\text{ V}$	$V_{CC} \times 0.3$		
$V_I$	Input voltage	0	5.5	V	
$V_O$	Output voltage	High or low state	0	$V_{CC}$	V
		3-state	0	5.5	
$I_{OH}$	High-level output current	$V_{CC} = 2\text{ V}$	-50	mA	
		$V_{CC} = 2.3\text{ V to }2.7\text{ V}$	-2		
		$V_{CC} = 3\text{ V to }3.6\text{ V}$	-8		
		$V_{CC} = 4.5\text{ V to }5.5\text{ V}$	-16		
$I_{OL}$	Low-level output current	$V_{CC} = 2\text{ V}$	50	mA	
		$V_{CC} = 2.3\text{ V to }2.7\text{ V}$	2		
		$V_{CC} = 3\text{ V to }3.6\text{ V}$	8		
		$V_{CC} = 4.5\text{ V to }5.5\text{ V}$	16		
$\Delta t/\Delta v$	Input transition rise or fall rate	$V_{CC} = 2.3\text{ V to }2.7\text{ V}$	200	ns/V	
		$V_{CC} = 3\text{ V to }3.6\text{ V}$	100		
		$V_{CC} = 4.5\text{ V to }5.5\text{ V}$	20		
$T_A$	Operating free-air temperature	-40	105	°C	

NOTE 4: All unused inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	$V_{CC}$	MIN	TYP	MAX	UNIT
$V_{OH}$	$I_{OH} = -50\ \mu\text{A}$	2 V to 5.5 V	$V_{CC}-0.1$			V
	$I_{OH} = -2\ \text{mA}$	2.3 V	2			
	$I_{OH} = -8\ \text{mA}$	3 V	2.48			
	$I_{OH} = -16\ \text{mA}$	4.5 V	3.8			
$V_{OL}$	$I_{OL} = 50\ \mu\text{A}$	2 V to 5.5 V			0.1	V
	$I_{OL} = 2\ \text{mA}$	2.3 V			0.4	
	$I_{OL} = 8\ \text{mA}$	3 V			0.44	
	$I_{OL} = 16\ \text{mA}$	4.5 V			0.55	
$I_I$	$V_I = 5.5\text{ V or GND}$	0 to 5.5 V			$\pm 1$	$\mu\text{A}$
$I_{OZ}$	$V_O = V_{CC}\text{ or GND}$	5.5 V			$\pm 5$	$\mu\text{A}$
$I_{CC}$	$V_I = V_{CC}\text{ or GND, } I_O = 0$	5.5 V			20	$\mu\text{A}$
$I_{off}$	$V_I\text{ or }V_O = 0\text{ to }5.5\text{ V}$	0			5	$\mu\text{A}$
$C_i$	$V_I = V_{CC}\text{ or GND}$	3.3 V		2.9		pF



# SN74LV374A-Q1

## OCTAL EDGE-TRIGGERED D-TYPE FLIP-FLOP WITH 3-STATE OUTPUTS

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timing requirements over recommended operating free-air temperature range,  $V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$  (unless otherwise noted) (see Figure 1)

		$T_A = 25^\circ\text{C}$		MIN	MAX	UNIT
		MIN	MAX			
$t_w$	Pulse duration, CLK high or low	5		5.5		ns
$t_{su}$	Setup time, data before CLK $\uparrow$	4.5		4.5		ns
$t_h$	Hold time, data after CLK $\uparrow$	2		2		ns

timing requirements over recommended operating free-air temperature range,  $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$  (unless otherwise noted) (see Figure 1)

		$T_A = 25^\circ\text{C}$		MIN	MAX	UNIT
		MIN	MAX			
$t_w$	Pulse duration, CLK high or low	5		5		ns
$t_{su}$	Setup time, data before CLK $\uparrow$	3		3		ns
$t_h$	Hold time, data after CLK $\uparrow$	2		2		ns

switching characteristics over recommended operating free-air temperature range,  $V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$  (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	$T_A = 25^\circ\text{C}$			MIN	MAX	UNIT
				MIN	TYP	MAX			
$f_{max}$			$C_L = 50\text{ pF}$	55	110		50		MHz
$t_{pd}$	CLK	Q		8.3	16.2		1	18.5	ns
$t_{en}$	$\overline{OE}$	Q		7.7	14.5		1	17.5	
$t_{dis}$	$\overline{OE}$	Q		5.9	14		1	16	
$t_{sk(o)}$					1.5				

switching characteristics over recommended operating free-air temperature range,  $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$  (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	$T_A = 25^\circ\text{C}$			MIN	MAX	UNIT
				MIN	TYP	MAX			
$f_{max}$			$C_L = 50\text{ pF}$	85	170		75		MHz
$t_{pd}$	CLK	Q		5.9	10.1		1	13.5	ns
$t_{en}$	$\overline{OE}$	Q		5.5	9.6		1	13	
$t_{dis}$	$\overline{OE}$	Q		4	8.8		1	10	
$t_{sk(o)}$					1				



**SN74LV374A-Q1**  
**OCTAL EDGE-TRIGGERED D-TYPE FLIP-FLOP**  
**WITH 3-STATE OUTPUTS**

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**noise characteristics,  $V_{CC} = 3.3\text{ V}$ ,  $C_L = 50\text{ pF}$ ,  $T_A = 25^\circ\text{C}$  (see Note 5)**

PARAMETER		MIN	TYP	MAX	UNIT
$V_{OL(P)}$	Quiet output, maximum dynamic $V_{OL}$		0.6	0.8	V
$V_{OL(V)}$	Quiet output, minimum dynamic $V_{OL}$		-0.5	-0.8	V
$V_{OH(V)}$	Quiet output, minimum dynamic $V_{OH}$		2.9		V
$V_{IH(D)}$	High-level dynamic input voltage	2.31			V
$V_{IL(D)}$	Low-level dynamic input voltage			0.99	V

NOTE 5: Characteristics are for surface-mount packages only.

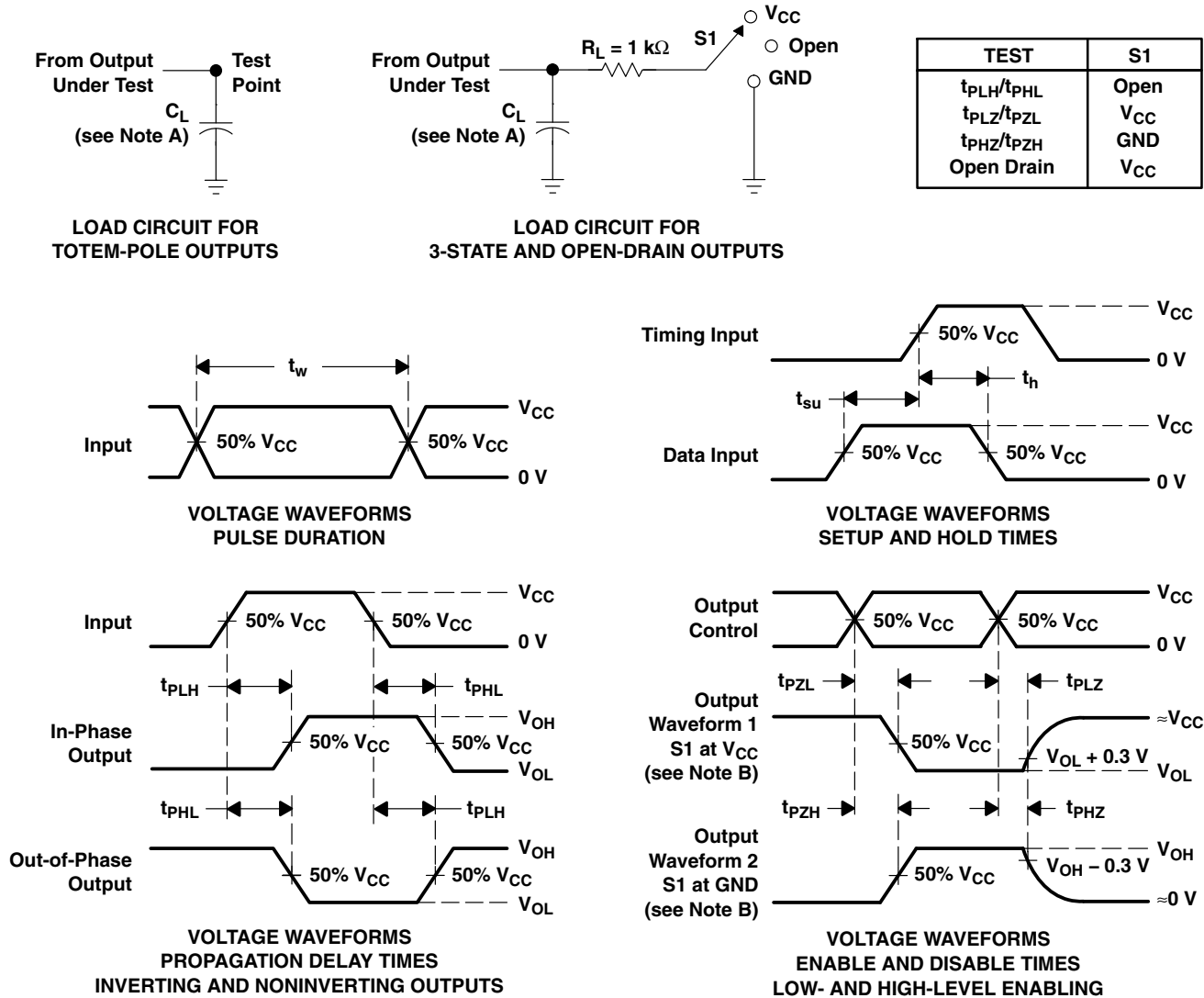
**operating characteristics,  $T_A = 25^\circ\text{C}$**

PARAMETER		TEST CONDITIONS	$V_{CC}$	TYP	UNIT	
$C_{pd}$	Power dissipation capacitance	Outputs enabled	$C_L = 50\text{ pF}$ , $f = 10\text{ MHz}$	3.3 V	21.1	pF
				5 V	22.8	

# SN74LV374A-Q1 OCTAL EDGE-TRIGGERED D-TYPE FLIP-FLOP WITH 3-STATE OUTPUTS

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## PARAMETER MEASUREMENT INFORMATION



- NOTES:
- A.  $C_L$  includes probe and jig capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
  - C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq 1\text{ MHz}$ ,  $Z_O = 50\ \Omega$ ,  $t_r \leq 3\text{ ns}$ ,  $t_f \leq 3\text{ ns}$ .
  - D. The outputs are measured one at a time, with one input transition per measurement.
  - E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
  - F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
  - G.  $t_{PHL}$  and  $t_{PLH}$  are the same as  $t_{pd}$ .
  - H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Samples (Requires Login)
SN74LV374ATPWRG4Q1	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LV374ATPWRQ1	OBSOLETE	TSSOP	PW	20		TBD	Call TI	Call TI	

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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**OTHER QUALIFIED VERSIONS OF SN74LV374A-Q1 :**

● Catalog: [SN74LV374A](#)

● Enhanced Product: [SN74LV374A-EP](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Enhanced Product - Supports Defense, Aerospace and Medical Applications



PW (R-PDSO-G20)

PLASTIC SMALL OUTLINE

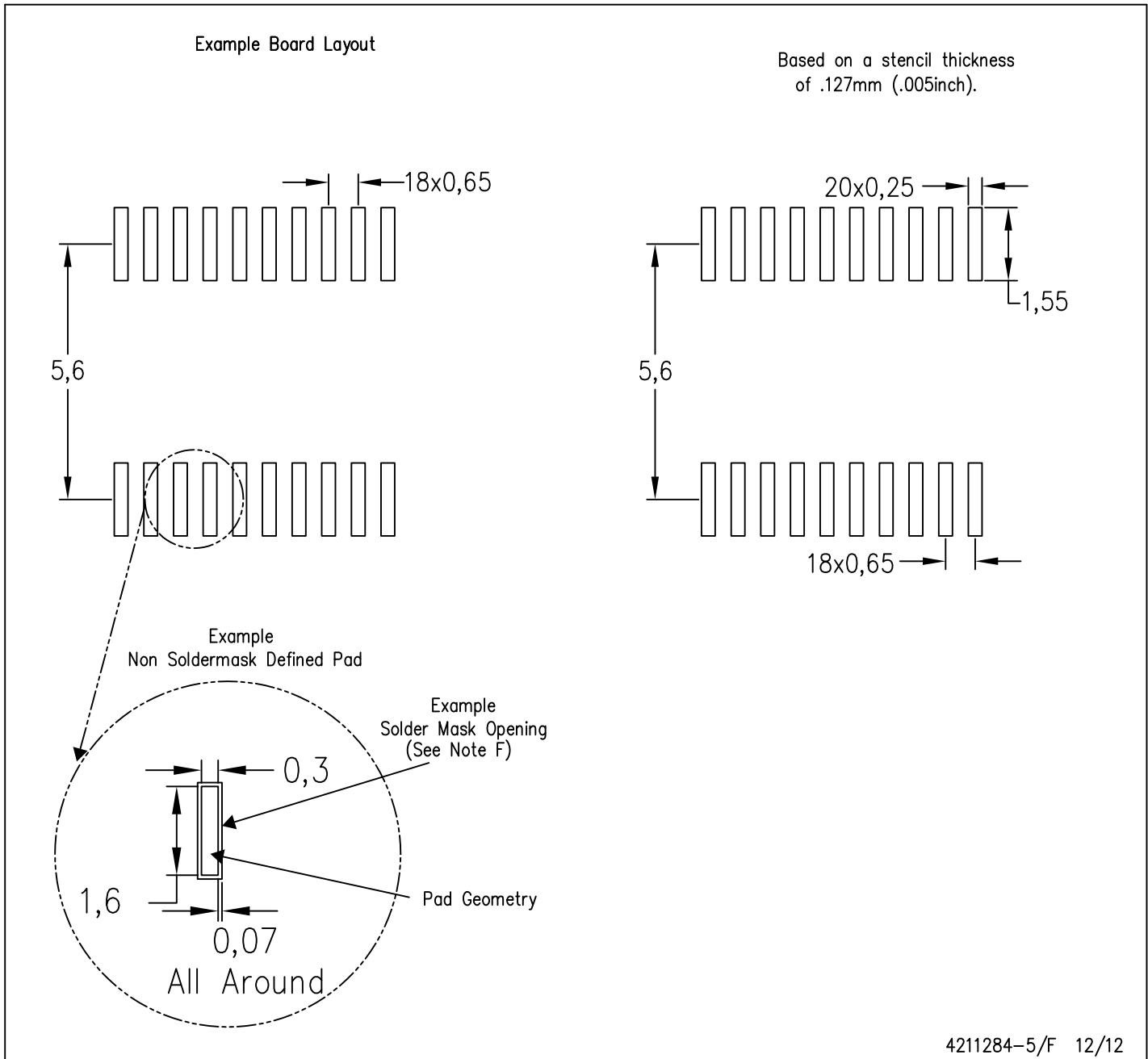


4040064-5/G 02/11

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  -  Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
  -  Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
  - E. Falls within JEDEC MO-153

PW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Publication IPC-7351 is recommended for alternate design.
  - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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